Unique ID Authority Response Date* Company unique ID Unique ID Authority Response Date* 2023-06-08	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
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Semil	upplier Informa	ation								,					
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Title - Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Product Enviro Compliance Requester Item Number Representative* Requester Item Number Reflow Cunit Type Content of the Number of Reflow Cycles Requester Item Number Representative* Requester Item Number Reflow Cycles Representative* Requester Item Number Representative* Requester Item Number Representative* Remail - Representative* Requester Item Number Representative Item Number Representati	Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Unit Ty 2023-06-08 LITEONFG 497.66 mg Each Anufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Termi	Product-Env-Stewar	rds	Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Authorized Representative* Title				Fitle - Representative			Phone - Representative*			Email - Representative*				
FOD3184SD 8PW 3A GD T&R 2023-06-08 LITEONFG 497.66 mg Each Instituting Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Seconds 1	Product-Env-Stewards Product				oduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
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or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of							
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight Unit of Measure Level Substance		Substance	CAS	Exempt	Weight	Unit of Measure	
Coupling Gel	0.45	mg	Supplier	Dimethyl Cyclosiloxanes	69430-24-6		0.045	mg
			Supplier	Trimethoxy(methyl)silane (C4H12O3Si)	1185-55-3		0.405	mg
Die	4.011	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.281	mg
			Supplier	Silicon (Si)	7440-21-3		3.73	mg
Die Attach	0.251	mg	Supplier	Silver (Ag)	7440-22-4		0.188	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.063	mg
Lead Frame	112.468	mg	Supplier	Silver (Ag)	7440-22-4		0.709	mg
			Supplier	Zinc (Zn)	7440-66-6		0.135	mg
			Supplier	Iron (Fe)	7439-89-6		2.59	mg
			Supplier	Copper (Cu)	7440-50-8		109	mg
			Supplier	Phosphorus (P)	7723-14-0		0.034	mg
Mold Compound-Black	375.6	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		15	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		86.3001	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		11.3	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		262.9999	mg
Plating	2.88	mg	Supplier	Tin (Sn)	7440-31-5		2.88	mg
Wire Bond - Au	2.0	mg	Supplier	Gold (Au)	7440-57-5		2	mg